



Designation: F1709 – 97(Reapproved 2008)

# Standard Specification for High Purity Titanium Sputtering Targets for Electronic Thin Film Applications<sup>1</sup>

This standard is issued under the fixed designation F1709; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon ( $\epsilon$ ) indicates an editorial change since the last revision or reapproval.

## 1. Scope

1.1 This specification covers pure titanium sputtering targets used as a raw material in fabricating semiconductor electronic devices.

1.2 This standard sets purity grade levels, physical attributes, analytical methods, and packaging.

1.2.1 The grade designation is a measure of total metallic impurity content. The grade designation does not necessarily indicate suitability for a particular application because factors other than total metallic impurity may influence performance.

## 2. Referenced Documents

2.1 *ASTM Standards*:<sup>2</sup>

E112 Test Methods for Determining Average Grain Size

## 3. Terminology

3.1 *Definitions of Terms Specific to This Standard*:

3.1.1 *finished product, n*—for the purposes of this standard, a “finished product” is a manufactured sputtering target, ready for use.

3.1.2 *material lot, n*—for the purpose of this standard, a “lot” is material melted into one ingot, and processed as one continuous batch in subsequent thermal-mechanical treatments.

## 4. Classification

4.1 Grades of titanium sputtering targets are defined in Table 1, based upon total metallic impurity content of the elements listed in Table 2. Impurity contents are reported in parts per million by weight (wt ppm). Higher purity grades, for example “5N5” and “6N”, may be provided, as agreed upon between the purchaser and the supplier.

<sup>1</sup> This specification is under the jurisdiction of ASTM Committee F01 on Electronics and is the direct responsibility of Subcommittee F01.17 on Sputter Metallization.

Current edition approved June 15, 2008. Published July 2008. Originally approved in 1996. Last previous edition approved in 2002 as F1709 – 97(2002). DOI: 10.1520/F1709-97R08.

<sup>2</sup> For referenced ASTM standards, visit the ASTM website, [www.astm.org](http://www.astm.org), or contact ASTM Customer Service at [service@astm.org](mailto:service@astm.org). For *Annual Book of ASTM Standards* volume information, refer to the standard’s Document Summary page on the ASTM website.

4.2 Purity grade and total metallic impurity levels are based upon the suite of elements listed in Table 2.

## 5. Ordering Information

5.1 Orders for pure titanium sputtering targets shall include the following:

5.1.1 Grade (see 4.1),

5.1.2 Special requirements concerning impurities, if required (see 6.1, 6.2, 6.3, 6.4),

5.1.3 Grain size, if required (Section 7),

5.1.4 Configuration (Section 8),

5.1.5 Certification required (Section 12), and

5.1.6 Whether or not a sample representative of the finished product is required to be provided by the supplier to the purchaser.

## 6. Impurities

6.1 The minimum suite of metallic impurity elements to be analyzed is defined in Table 2. Acceptable analysis methods and detection limits are specified in Section 11. Elements not detected will be counted and reported as present at the minimum detection limit (“mdl”). Additional elements may be analyzed and reported as agreed upon between the purchaser and the supplier, but these shall not be counted in defining the grade designation.

6.2 Cesium, chlorine, phosphorus, and tantalum present particular analysis problems. The limits, analysis method, and mdl may be as agreed upon between the purchaser and the supplier.

6.3 Nonmetallic elements which shall be analyzed and reported are carbon, hydrogen, nitrogen, oxygen, and sulfur. Maximum limits for nonmetallic impurities shall be as agreed upon between the purchaser and the supplier.

6.4 Acceptable limits and analytical techniques for particular elements in critical applications may be agreed upon between the purchaser and the supplier.

## 7. Grain Size

7.1 The average and the maximum grain size shall be as agreed upon between the purchaser and the supplier.